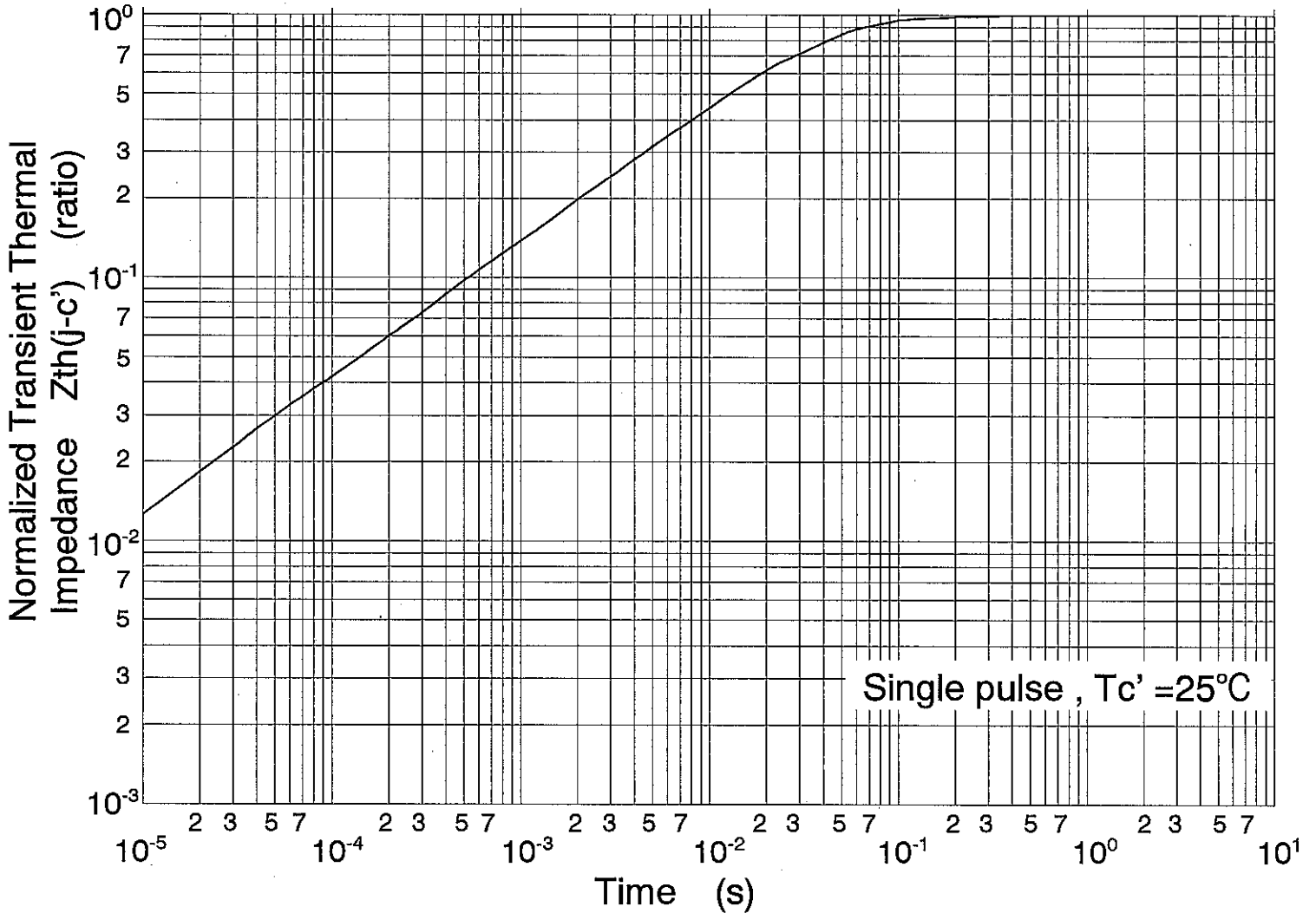


APPLICATION NOTE	Prepared by	<i>S. Uchida</i>	Rev	
	Approved by	<i>M. Yamamoto Nov. 12. 2002</i>		

Transient Thermal Impedance Characteristics under the chip
(IGBT part & FWD part)
CM900DU-24NF / CM1400DU-24NF



CM900DU-24NF

IGBT part : per unit base= $R_{th(j-c')}=0.021^\circ\text{C/W}$

FWD part : per unit base= $R_{th(j-c')}=0.034^\circ\text{C/W}$

CM1400DU-24NF

IGBT part : per unit base= $R_{th(j-c')}=0.014^\circ\text{C/W}$

FWD part : per unit base= $R_{th(j-c')}=0.023^\circ\text{C/W}$